Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-14 (canceled)

Claim 15 (currently amended): A fiber optic communications module, comprising:

a set of optical fibers supported in an optical ferrule having a ferrule alignment ~~structure,~~ structure;

an optoelectronic device; and

a carrier including:

a) a carrier alignment structure adapted for cooperating with the ferrule alignment structure of said optical ferrule and aligning said carrier with said optical ferrule,

b) a window section,

c) a transparent film layer disposed on ~~the~~ a surface of the carrier over said window section, and

d) an alignment mark placed on said transparent film layer and precisely aligned relative to the carrier alignment structure for positioning ~~an~~ the optoelectronic ~~device; and~~ device, and wherein

the ~~an~~ optoelectronic device ~~having~~ includes a set of photoactive components corresponding to said set of optical fibers in said optical ferrule which is mounted on said transparent film layer of said carrier with reference to said alignment mark over said window section so as to be precisely aligned with said carrier alignment structure so that said photoactive components are aligned for optical communication through said window section with said set of optical fibers when said carrier is coupled to said optical ferrule.

Claim 16 (original): The fiber optic communications module according to claim 15, wherein:

said photoactive components comprise vertical cavity surface-emitting lasers.

Claim 17 (original): The fiber optic communications module according to claim 15, wherein:

said photoactive components comprise PIN photodiodes.

Claim 18 (original): The fiber optic communications module according to claim 15, wherein:

said carrier comprises a silicon substrate.

Claim 19 (original): The fiber optic communications module according to claim 18, wherein:

said silicon substrate carrier includes metal traces for conducting signals and providing power to said optoelectronic device.

Claim 20 (currently amended): The fiber optic communications module according to claim 18, wherein:

said transparent film layer is composed of a dielectric material deposited on said silicon substrate using photolithography techniques.

Claim 21 (currently amended): The fiber optic communications module according to claim 18, wherein:

said alignment mark comprises one or more metal traces deposited on said transparent film layer using photolithography techniques.

Claim 22 (currently amended): The fiber optic communications module according to claim 18, further including:

a set of metal traces deposited using photolithography techniques as a grid on said transparent film layer over said window section for use in suppressing EMI emissions.

Claim 23 (currently amended): The fiber optic communications module according to claim 18, wherein:

said photoactive components are arranged in a first linear array, and wherein

said set of optical fibers are arranged in a second linear array corresponding to said first linear array of photoactive components, and wherein

~~and~~ said module further includes a set of lenses disposed in a lens array for collecting and focusing light passing between said set of optical fibers and said photoactive components.

Claims 24-50 (canceled)